

MINUTES  
 S-1 General Session  
 Chateau Bourbon  
 New Orleans, LA 70112  
 Tuesday April 28, 2009

**1.0 Call to Order - Circulate Membership Roster**

Meeting called to order at 8:05 am by Chairman Mike Lauri

**2.0 Committee Organization and Procedures**

2.1 Membership Intros were conducted and Roster circulated.

The attendance was as follows:

<u>NAME</u>	<u>COMPANY</u>
Michael Lauri (by phone/webex )	IBM
Chris Reynolds (by phone/webex )	AVX
Dave Richardson	Vishay
Joe Biernacki	SEI Electronics
Laird Macomber	CDE
Brian Piscitelli	KOA
Lanney McHargue	Murata
Jayson Young	Kemet Electronics
Mary Carter Berrios	Kemet Electronics
Bob Willis	ECA
Ray Teken (by phone/webex)	ECA
Ed Mikoski	TIA

A quorum was present. 8 of 10 member companies present at meeting.

<u>Member Organizations Present</u>	<u>Present at this Meeting (Spring 2009)</u>	<u>Present at the Meeting (Fall 2008)</u>	<u>Present at the Meeting (Spring 2008)</u>
AVX	Y	N	Y
Cornell Dubilier	Y	Y	Y
IBM	Y	Y	Y
Kemet	Y	Y	Y
KOA Speer Electronics	Y	Y	Y
SOC America Inc.	N	Y	Y
SEI Electronics	Y	N	Y
TDK	N	Y	Y
Vishay	Y	Y	Y
Murata Electronics	Y	Y	Y

<b><u>Other Organizations</u></b>
<b><u>Present</u></b>
ECA
TIA

**2.1 and 2.2 Approval of Agenda and Previous Minutes** – Approved Unanimously

**2.3 Correspondence** – NONE

**2.4 Review of Committees Scope-** To provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers. No changes required at this time.

**3.0 ECA Environmental Update – ECA/TIA**

Bob Willis of ECA gave a brief update on a presentation that Jim Mathews gave involving IEC and IECQ at the TIA. It discussed certifying companies to certify themselves in various countries for EI, Rohs, Reach, WEE etc.

Ed Mikoski of TIA then took the committee through the EIA-TRACK which is coordinating Environmental issues throughout the world. TIA took over this from EIA and has now updated it to make it current, it also resides on the TIA website. This EIA-TRACK covers over 600 plus regulations being tracked by many different countries. Its growing through alliances with CEA, ITEC and ECCB, and they are also in discussions of adding NEMA, CTIA, SEMI, NAM, and BICSI. There are 135 subscriber companies to date and they have recently added countries such as India, Thailand, South Korea, Hong Kong to its list. Soon more BRIC countries will be added for tracking like Russia etc. Member companies get regulatory alerts and special reports from this tool. New reports were available for China WEE, EU Battery Directives and Full India report.

**4.0 Presentations** - NONE

**5.0 Old Business**

**5.1 Mike Lauri of IBM brought up that J-STD-075 will be updated starting in the May/June timeframe.** The goal is to add rework to this document as well as to try and simplify the coding scheme if at all possible. Conference calls will be schedule over the next few months so we can have a preliminary draft prior to the fall summit.

**5.2 IPC 709 “Definition of maximum limits on the low halogens bromine and chlorine used in materials for certain electronic components and assemblies.”** Was rejected in the voting process.

There were over 75pages of comments both editorial and technical in nature which need to be resolved prior to voting again. IBM will keep this S1 committee aware of the

changes to this document as needed and send update of IPC-709 out to S1 members as it becomes available.

5.3 Cobalt Dichloride is on the REACH list of substances of very high concern (SVHC) and Jayson Young of Kemet brought this topic up for discussion. The concern is SVHC substances generally go onto the banned list next, Kemet brought up that other available non-cobalt alternatives can conform to J-STD-033B and have different color schemes. The IC industry is looking at a new HIC card without cobalt dichloride, and as it stands today about 1/3 of industry has converted away from the cobalt dichloride HIC. Kemet stated they are trying to get around this issue by lowering the amount of cobalt in the HIC so they do not have to report.

5.4 Mike Lauri of IBM also proposed a joint meeting location for ECA, JEDEC and IPC in the 2010 timeframe to work on more joint standards. Other areas being considered are solderability, shelf life, materials declarations etc... This will be tabled and again discussed at next meeting. S1 recommends to be brought up again at the ECA board meeting for consideration in 2010.

## **6.0 New Business**

6.1 We briefly discussed the new ultra capacitor subcommittee and if any new specifications or topics are needed please bring these to the new P2.7 committee meeting later in the week.

6.2 Ed Mikoski of TIA also requested us to provide input on electronic tool improvements, process improvements, on line voting improvements to be provided to Bob Willis of ECA over the next several months.

6.3 It was suggested that HIS (Global) be invited to a future meeting to discuss their archive and spec procurement features.

**7.0 Future Meetings** – The next meeting Fall 2009 will be at the Doubletree Hotel Savanna Georgia on Oct. 5-9, 2009. The committee voted to go to Orlando, Florida in the Spring 2010.

## **8.0 Action Items –**

1. Chairmen of S1 will keep this committee aware of the changes to this document as needed and send update of IPC-709 out to S1 members as it becomes available.

**9.0 Adjournment** – Meeting was adjourned at 10:00 AM.